Abstracts

Development of microwave package models utilizing on-wafer characterization techniques

C. Chun, A.-V. Pham, J. Laskar and B. Hutchison. "Development of microwave package models utilizing on-wafer characterization techniques." 1997 Transactions on Microwave Theory and Techniques 45.10 (Oct. 1997, Part II [T-MTT] (Special Issue on Interconnects and Packaging)): 1948-1954.

A package characterization technique using coplanar waveguide (CPW) probes and line-reflect-match (LRM) calibrations for surface-mountable packages is presented. CPW-to-package adapters (CPA) are fabricated on alumina substrates to mount and measure the high-frequency response of plastic packages. Offset CPA standards in conjunction with an LRM calibration are used to de-embed the response of the adapters from the measured S-parameters. Application of this method is demonstrated by characterizing and modeling surface-mount microwave plastic packages.

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